TENCON 2019

17-20 October 2019 | Kochi, Kerala

Special Session on Advanced On-chip Packaging and Systems

Call for Paper

Special Session Track on

Advanced On-chip Packaging and Systems

- •3D-ICs/TSVs/Interposers
- •Testing on 3D-IC and SiP
- •Signal and Thermal Integrity
- •Power Integrity/Power Distribution Networks (PDNs) /Ground Noise
- •Computational Electromagnetics and Multi-physics Methods for SI/PI/TI Analysis
- •Thermal Management Design for 3D-ICs and SiP
- •Design and Modeling for High-speed Channels and Interconnects
- •High speed serial links jitter budgeting
- •Jitter segregation algorithms and tools
- •Time / Frequency Domain Measurement Techniques
- •Power supply induced jitter and transfer functions.
- •Nanoelectronics for 3D-ICs and SiP.
- Others

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General Co-Chairs S. M. Sameer, Chair, IEEE Kerala Section, Sarada Jayakrishnan

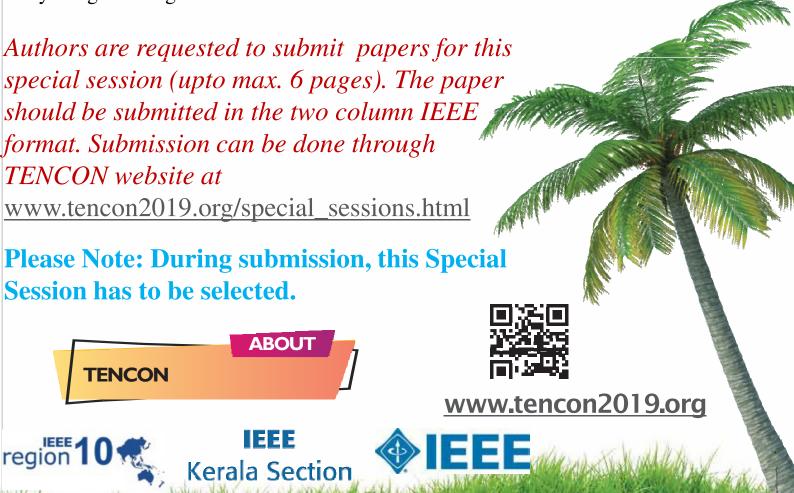
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Special Session Technical Enquiries: mr.yashagrawal@gmail.com

TENCON website at

Session has to be selected.



ORGANIZING COMMITTEE

Special Session Track Chair

Rohit Sharma. IIT Ropar

Yash Agrawal, DA-IICT Gandhinagar

Girish Kumar Mekala, VJIT Hyderabad

IMPORTANT DATES

Papers Submission Submission Deadline : June 30, 2019 Paper Acceptance Date : August 15, 2019 Camera-Ready : August 30, 2019